Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
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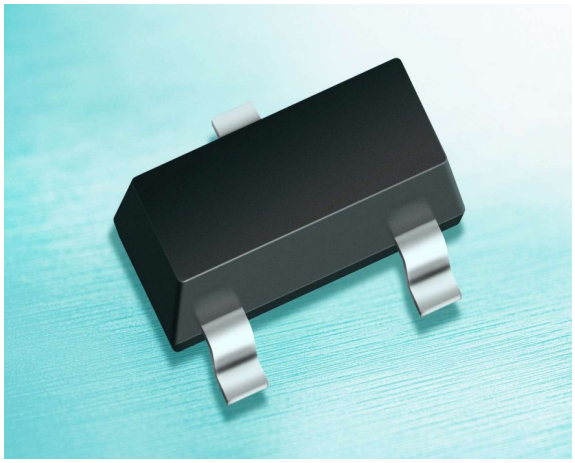
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

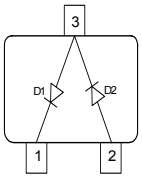
Silicon RF Schottky Diodes

- Low barrier type for mixer applications
  up to 12 GHz, phase detectors and modulators
- Pb-free (RoHS compliant) package

RoHS



BAT15-04R



ESD (**E**lectro**s**tatic **d**ischarge) sensitive device, observe handling precaution!

Type	Package	Configuration	L_S(nH)	Marking
BAT15-04R*	SOT 23	reverse series pair	1.5	4R

*preliminary

Maximum Ratings at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	4	V
Forward current	I_F	110	mA
Junction temperature	T_j	150	°C
Operating temperature range	T_{op}	-55 ... 150	
Storage temperature	T_{stg}	-65 ... 150	

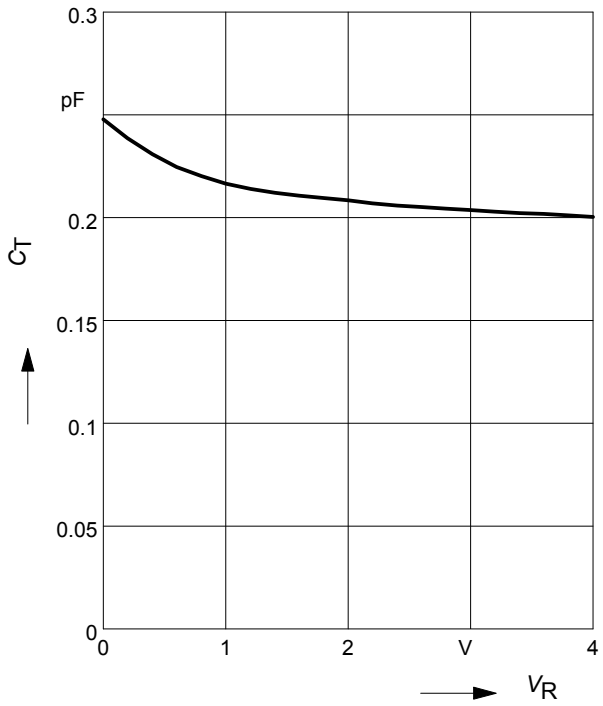
Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Breakdown voltage $I_{(BR)}$ = 10 µA	$V_{(BR)}$	4	-	-	V
Forward voltage I_F = 1 mA	V_F	0.2	0.25	0.3	
Forward voltage matching[1)] I_F = 1 mA	ΔV_F	-	-	10	mV
AC Characteristics					
Diode capacitance V_R = 0 V, f = 1 MHz	C_T	-	0.25	-	pF
Differential forward resistance I_F = 5 mA	R_F	-	-	18	Ω

[1] ΔV_F is the difference between lowest and highest V_F in a multiple diode component.

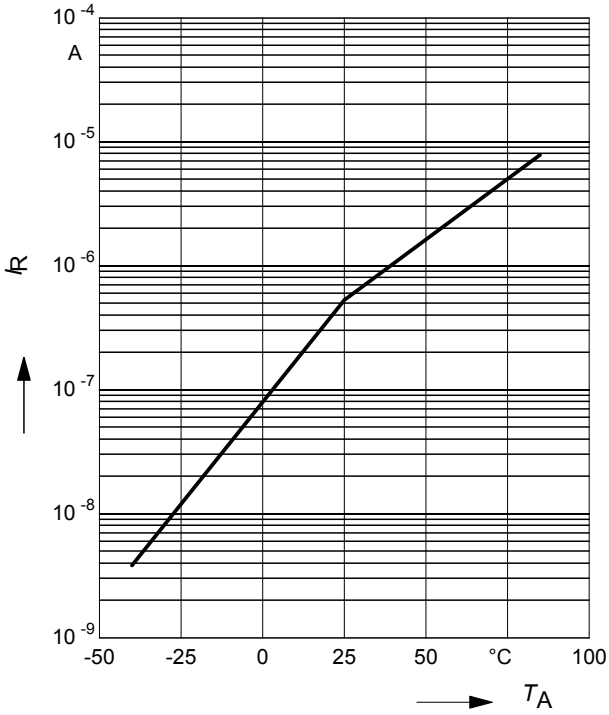
Diode capacitance $C_T = f(V_R)$

f = 1MHz



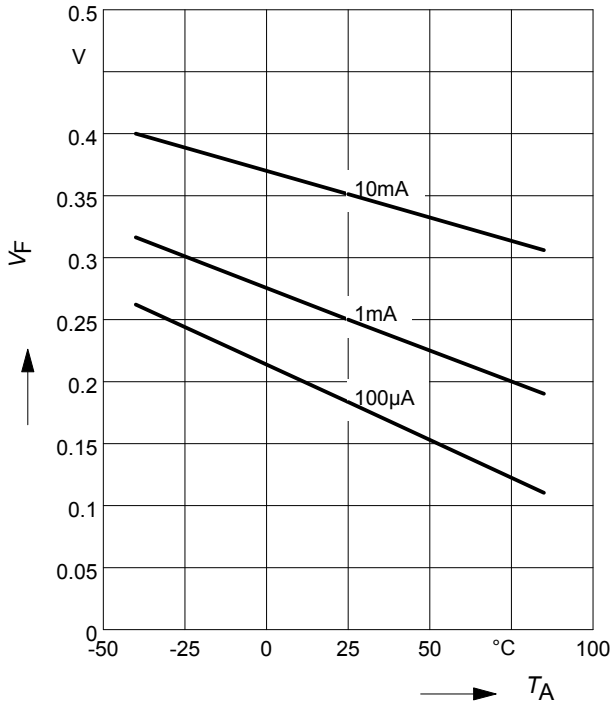
Reverse current $I_R = f(V_R)$

T_A = Parameter



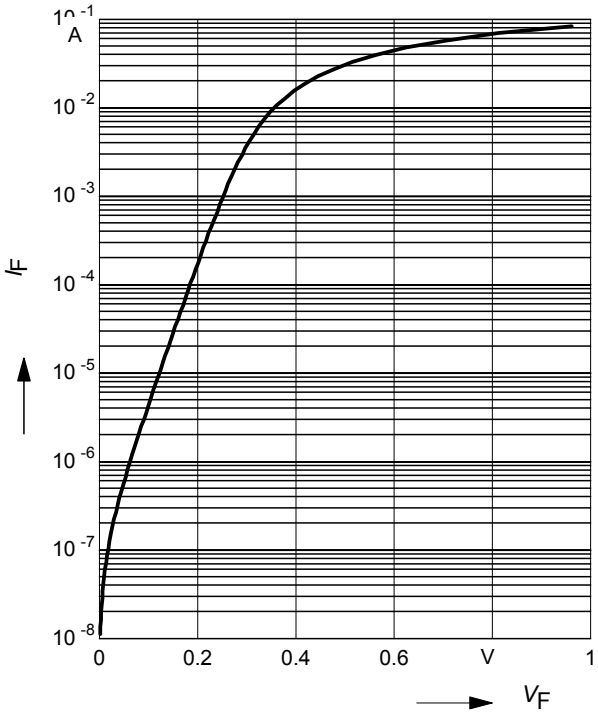
Forward Voltage $V_F = f(T_A)$

I_F = Parameter

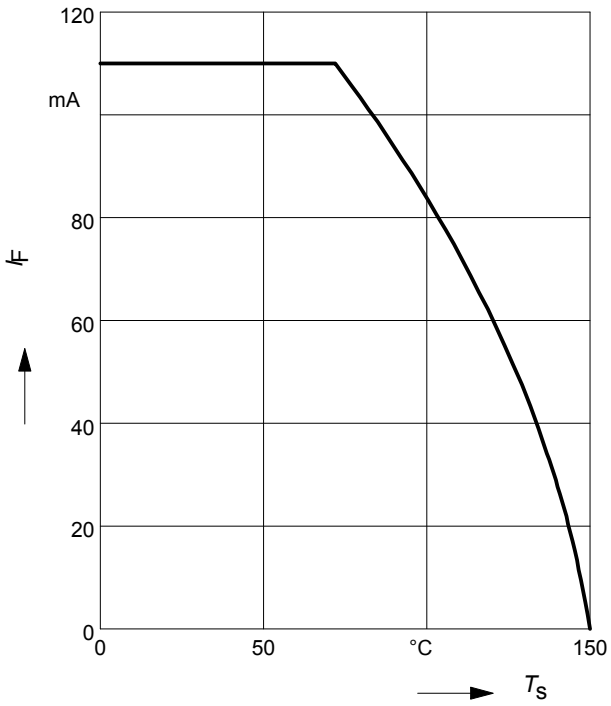


Forward current $I_F = f(V_F)$

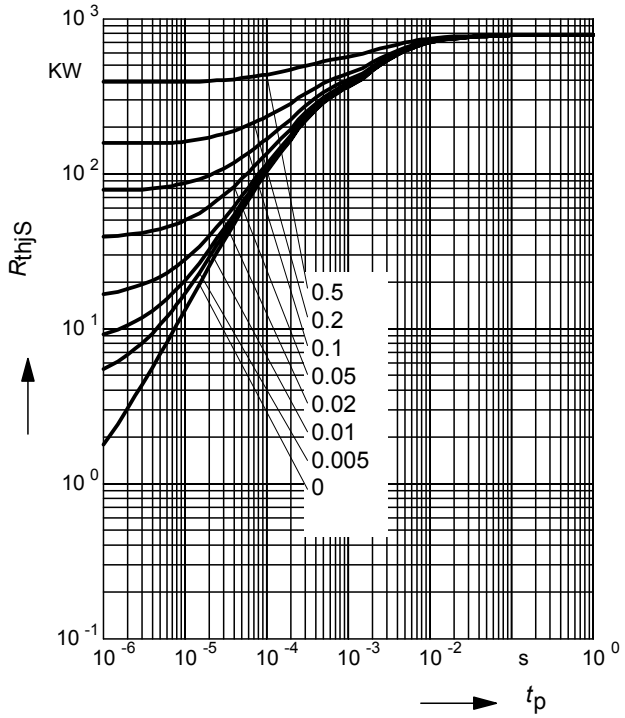
T_A = 25°C



Forward current $I_F = f(T_S)$

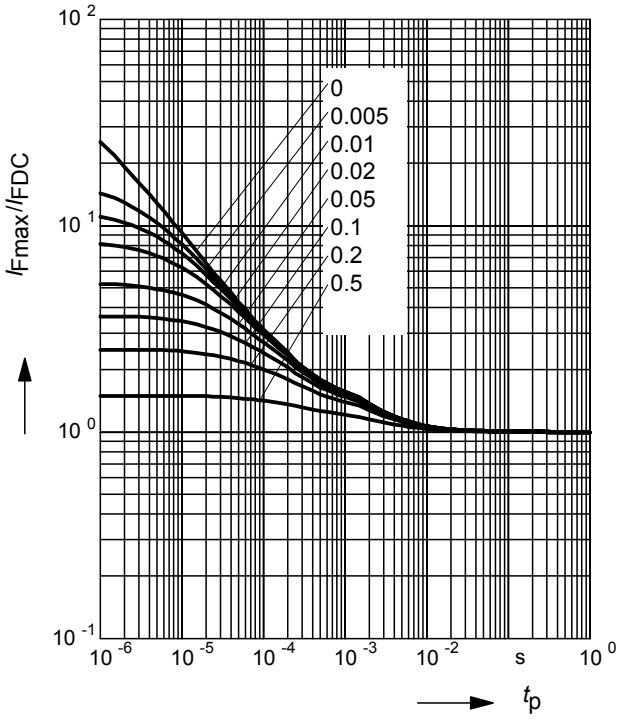


Permissible Puls Load $R_{thJS} = f(t_p)$

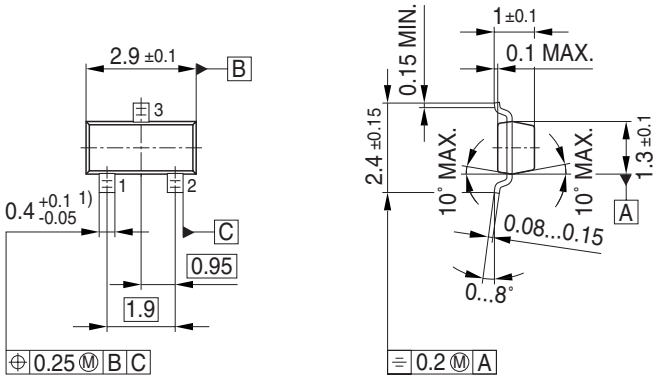


Permissible Pulse Load

$I_{Fmax}/ I_{FDC} = f(t_p)$

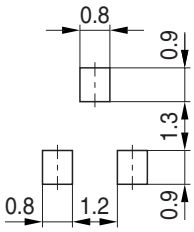


Package Outline

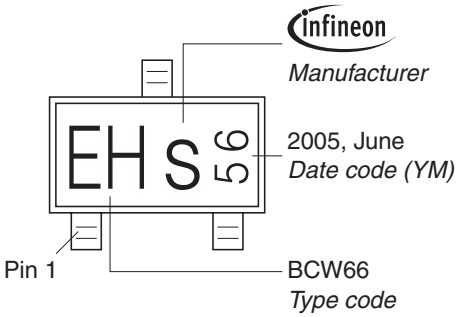


1) Lead width can be 0.6 max. in dambar area

Foot Print

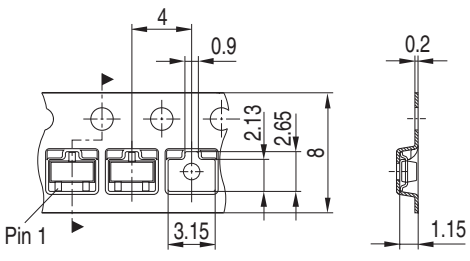


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



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